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**Analysis Of Foreign Matter Materials
Related To The Die Attach Process
Of Semiconductor Device Packaging**

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**Institute of Postgraduate Studies & Research
University of Malaya
Kuala Lumpur
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**Dissertation submitted in partial fulfillment
for the degree of
Master of Technology
(Material Science)**

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DECLARATION

I hereby declare that the work reported in this dissertation is my own, unless specified and duly acknowledged by quotation.

31st August 1999

(Tengku Elisa Bustaman)

PREFACE

The research on the effects of the foreign matter materials present at the die attach process of semiconductor device packaging on the device functionality was done in Motorola (M) Sdn. Bhd., Petaling Jaya. This study was in partial fulfillment of the degree of Master of Technology (Material Science).

In the University of Malaya, I was supervised by Professor S. Radhakrishna from the Institute of Postgraduate Studies and Research and was co-supervised by Dr. Aziz Hassan from the Chemistry Department from 1996 to 1998. When Professor S. Radhakrishna ended his tenure with the university in 1998, Dr. Aziz Hassan took over the supervisory duties with Associate Professor Dr Alias Daud as co-supervisor.

While in Motorola (M) Sdn Bhd, I was advised by Engineering Manager of the Hermetic Department, Ms. LC Tan.

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ABSTRACT

The purpose of this study is to investigate the effects of the presence of foreign matter (FM) that appears during the die attach process of semiconductor device packaging on the functionality of semiconductor devices (devices). This study also covers the investigation on sources of FM, and suggests methods of reducing the presence of FM during the die attach process of devices. Actual in-process rejects were collected to categorize the different types of FM and to quantify the actual impact of the different FM categories on device manufacturing yield. Some of these rejects were sent for electrical testing to determine whether FM adversely affects the end-functionality of a device. This study concluded that the presence of FM did not adversely affect the end-functionality of a device. Some of the rejects were sent for elemental analysis to determine whether the FM types seen were of conductive material that would produce adverse effects on the end-functionality of a device. Analysis done showed that the FM consists of non-conductive Carbon elements. Simulations were also conducted to determine the sources of FM. FM sources identification allows us to suggest methods of reducing the presence of FM. With the results of this study, the reject criteria for FM in Motorola (M) Sdn. Bhd. had been revised and the preventive action taken has reduced the amount of FM found at the die attach process, thus improving the manufacturing yield of the semiconductor devices.

CONTENTS

Declaration	i
Preface	ii
Acknowledgement	iii
Abstract	iv
1 Introduction	1
1.1 The Semiconductor Industry	1
1.2 The Hermetic Package Assembly Process	4
1.3 Die Attach Process	12
1.4 Die Attach Materials	14
1.4.1 Direct Materials	14
1.4.2 Indirect Materials	15
1.5 Die Attach Defects	18
1.5.1 Present Defect Levels	18
1.5.2 Present Accepted Criteria	20
1.6 About This Report	20
2 Experimental Techniques	24
2.1 Categorization Of FM Defects	24
2.2 FM Mapping	25
2.3 Simulation Of FM Rejects	29
2.4 Material Analysis	29
2.4.1 Elemental Analysis	30
2.4.2 Depth Analysis	32

3.4	Material Analysis	64
3.4.1	Elemental Analysis	64
3.4.2	Depth Analysis	70
3.5	Electrical Analysis	72
3.5.1	Lead-To-Lead electrical measurements	72
4	Functional Testing Results And Discussion	74
4.1	Functional Testing	74
4.2	Failure And FM Location Correlation	76
4.3	Reliability Testing	77
4.3.1	Functional Reliability Testing	77
4.3.2	Failure and FM Location Correlation	78
4.3.3	PIND Test	78
5	Conclusion and Suggestion For Further Work	80
5.1	Conclusion	80
5.2	FM Reject Criteria Relaxation	81
5.3	Suggestions for Further Work	84
	References	85
	Appendix A	87
	Appendix B	108